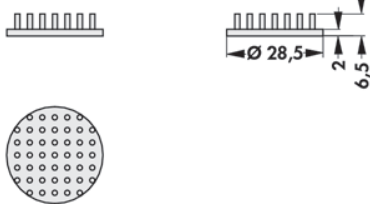
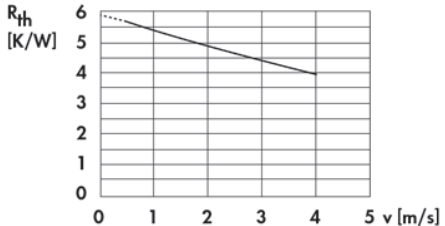
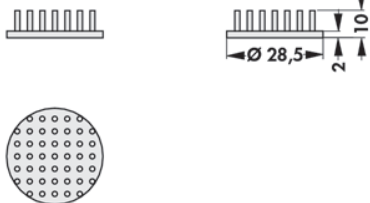
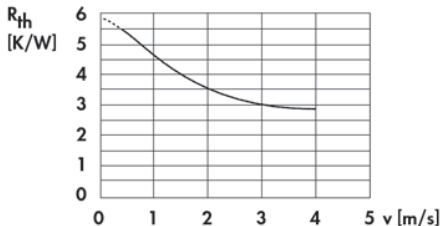
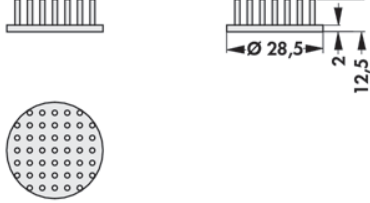
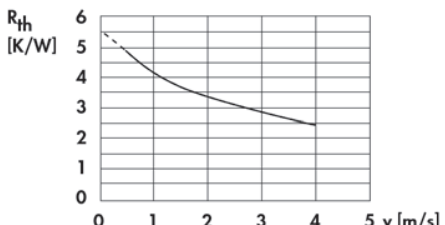
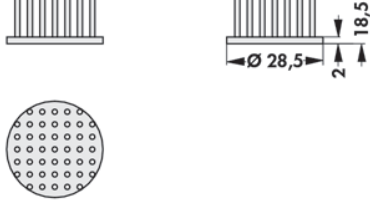
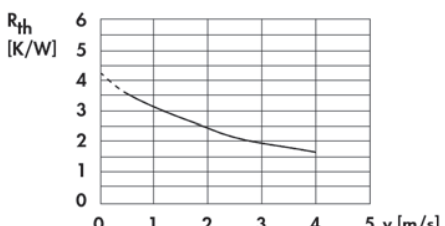
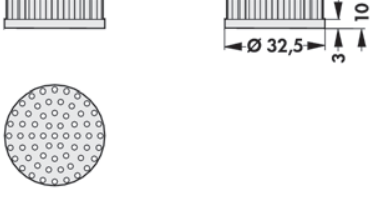
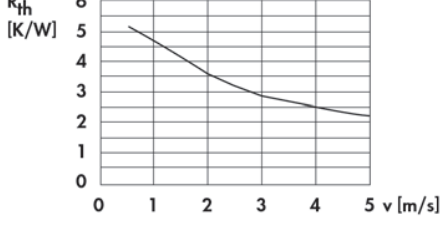
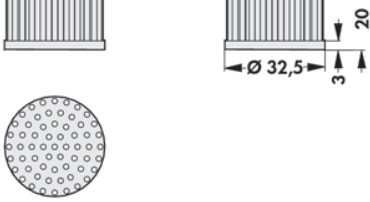
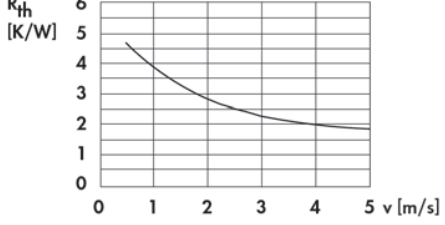
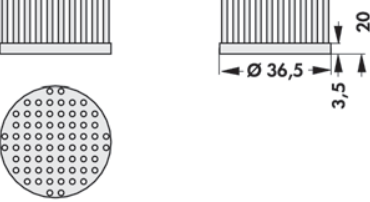
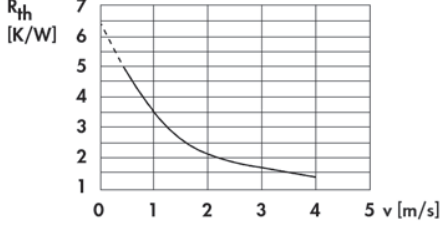


Pin heatsinks

Round

<p><b>art. no.</b></p> <p><b>ICK S R 28,5 x 6,5</b> WLF ... D 28,5 weight: 4.41 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 28,5 x 10</b> WLF ... D 28,5 weight: 5.16 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 28,5 x 12,5</b> WLF ... D 28,5 weight: 5.7 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 28,5 x 18,5</b> WLF ... D 28,5 weight: 6.98 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 32,5 x 10</b> WLF ... D 32 weight: 9.7 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 32,5 x 20</b> WLF ... D 32 weight: 13.8 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 36,5 x 20</b> WLF ... D 36,5 weight: 17.59 g</p>		

Thermal conductive glue → E 15  
 Thermal conductive paste → E 13  
 SMD-heatsinks → B 38 – 40  
 Thermal conduct. foil WLFT 404/405 → E 5

Mounting material for semiconductor → E 37 – 41  
 Thermal conduct. foil WLFT 404/405 → E 5  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

## Pin heatsinks

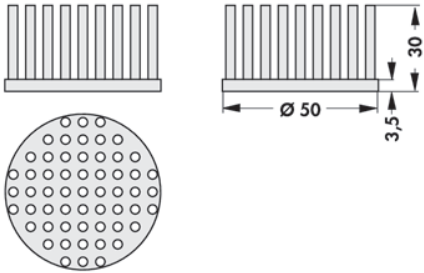
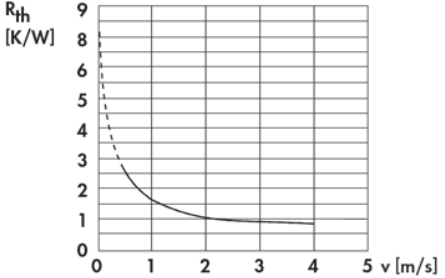
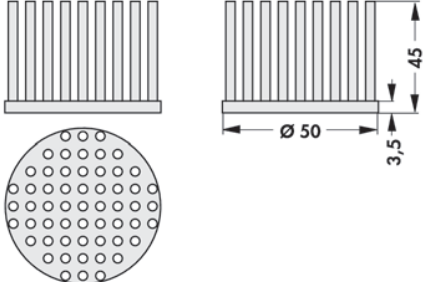
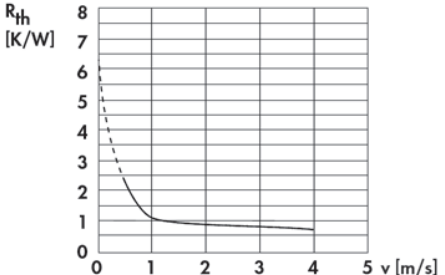
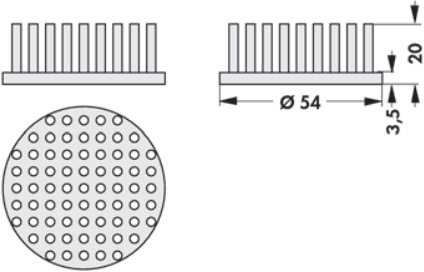
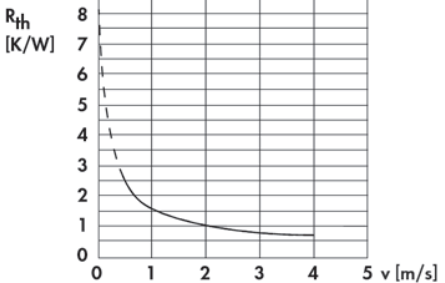
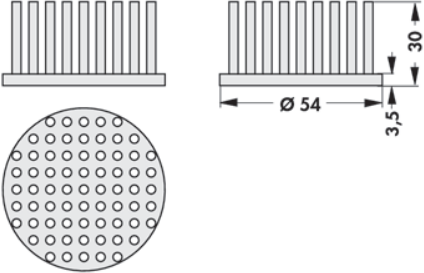
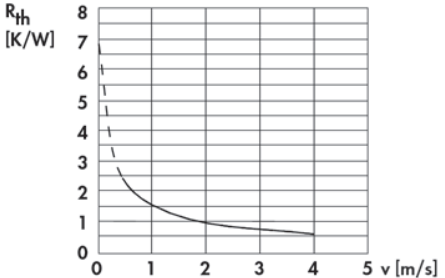
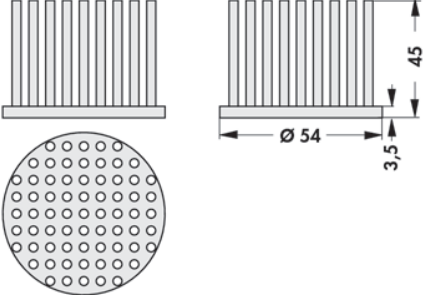
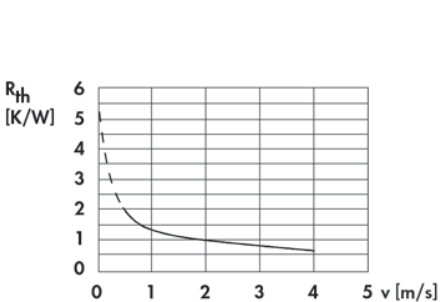
<p><b>art. no.</b></p> <p><b>ICK S R 40 x 10</b> WLF ... D 40 weight: 15.85 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 40 x 20</b> WLF ... D 40 weight: 21.96 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R A 40 x 20</b> WLF ... D 40 weight: 22.18 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 40 x 30</b> WLF ... D 40 weight: 29.24 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 50 x 10</b> WLF ... D 50 weight: 22 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 50 x 20</b> WLF ... D 50 weight: 34.39 g</p>		

**B 27**

Thermal conductive glue → E 15  
Thermal conductive paste → E 13  
SMD-heatsinks → B 38 – 40  
Thermal conduct. foil WLFT 404/405 → E 5

Mounting material for semiconductor → E 37 – 41  
Thermal conduct. foil WLFT 404/405 → E 5  
Hole pattern → A 21  
Technical introduction → A 2 - 7

Pin heatsinks

<p><b>art. no.</b></p> <p><b>ICK S R 50 x 30</b> WLF ... D 50 weight: 45.28 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 50 x 45</b> WLF ... D 50 weight: 61.59 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 54 x 20</b> WLF ... D 54 weight: 40.94 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 54 x 30</b> WLF ... D 54 weight: 54.11 g</p>		
<p><b>art. no.</b></p> <p><b>ICK S R 54 x 45</b> WLF ... D 54 weight: 73.86 g</p>		

Thermal conductive glue → E 15  
 Thermal conductive paste → E 13  
 SMD-heatsinks → B 38 - 40  
 Thermal conduct. foil WLFT 404/405 → E 5

Mounting material for semiconduct. → E 37 - 41  
 Thermal conduct. foil WLFT 404/405 → E 5  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7